

PCB CLEANING

FIND THE RIGHT CHEMISTRY THAT FITS YOUR PROCESS

Electronics assembly or circuit board cleaning is important to consider for reliable and dependable products. No matter what your PCB cleaning process, choosing the right chemistry is crucial.

AQUEOUS SOLUTIONS FOR ALL FLUX RESIDUES

AQUANOX® A4727 *(Enhanced Aqueous Assembly Cleaner)*

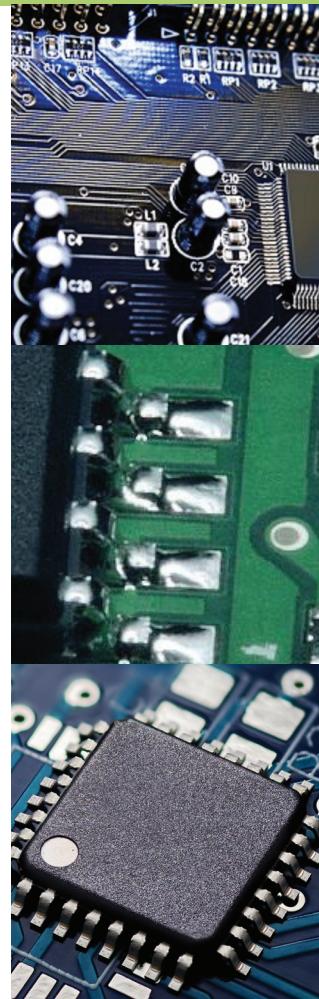
An award-winning electronics assembly cleaning solution that provides exceptional results when cleaning printed circuit boards and advanced packaging assemblies. A4727 has been lab and field-tested in spray-in-air processes and has proven effective on all solder flux residues, including the most difficult Pb-free and no-clean formulations.

AQUANOX® A4625(B) *(Aqueous Batch Cleaning Solution)*

Developed specifically to remove all types of solder pastes and flux residues from printed circuit board assemblies, including the latest lead-free solder paste formulas. Originally designed to address the challenges of batch cleaning systems, A4625B is also very effective when used in in-line washers.

AQUANOX® A4626 *(Next Generation Aqueous Cleaning Solution)*

A next generation cleaning chemistry designed to quickly remove the latest polymeric no-clean flux residues, while providing superior results on traditional lead-free and eutectic tin-lead residues as well. Easy to use and control, A4626 is environmentally friendly, has a long tank life and is safe for multi-pass applications.



WATER SOLUBLE (OA) FLUX RESIDUES ONLY

AQUANOX® A4382 *(OA Flux Residue Cleaning Chemistry)*

A near-neutral range pH chemistry designed with superior cleaning efficacy with great material compatibility on surface mount assemblies. A4382 most effectively cleans organic acid flux residues at lower concentrations.

SEMI-AQUEOUS SOLUTIONS FOR ALL FLUX RESIDUES

MICRONOX® MX2322

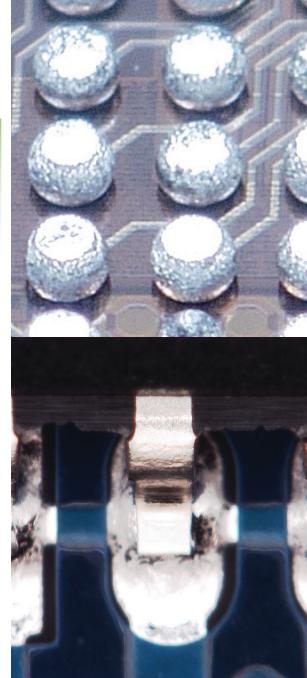
(*Semi-Conductor & Advanced Packaging Cleaning Chemistry*)

A semiconductor grade semi-aqueous solvent that is designed to clean all types of paste fluxes common in wafer bumping, wafer-level packaging, die-attach, flipchip and SiP containing copper pillar. MX2322 demonstrates its excellent cleaning performance and benefits in single-wafer spray-in-air tools as well as all immersion cleaning systems.

IONOX® FCR

(*High-Strength, Semi-Aqueous Electronics Cleaner*)

A high-strength, concentrated cleaner containing a blend of organic solvents and inhibitors. FCR is engineered to remove organic acid, rosin and no-clean flux residues from electronic assemblies, advanced packages, hybrid and SMT substrates.



BENCHTOP REWORK/MANUAL SOLDERING

CYBERSOLV® 141-X

(*Precision Aerosol Solvent Cleaner*)

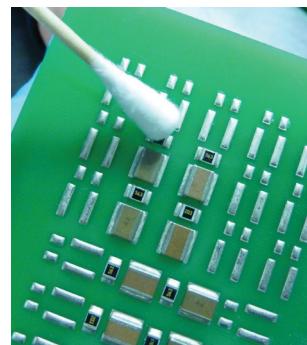
A non-flammable, solvent-based cleaning fluid designed for bench-top cleaning needs removing rosin, resin and synthetic polymeric flux residues from electronic circuitry. CYBERSOLV 141-X is ideally suited for cleaning through-hole and SMT electronic assemblies, connectors, cables and hybrid cables.



CYBERSOLV® C8882

(*Manual Benchtop Cleaner*)

A solvent-based cleaning fluid designed to remove solder paste and flux residues from processed, hand-soldered and mis-printed PCBs. C8882 is effective when cleaning isolated areas, rinses freely, and dries residue-free.



At KYZEN, we specialize in finding the right chemistry that works best for your process. Contact us today and our experts will help you achieve your cleaning goals!